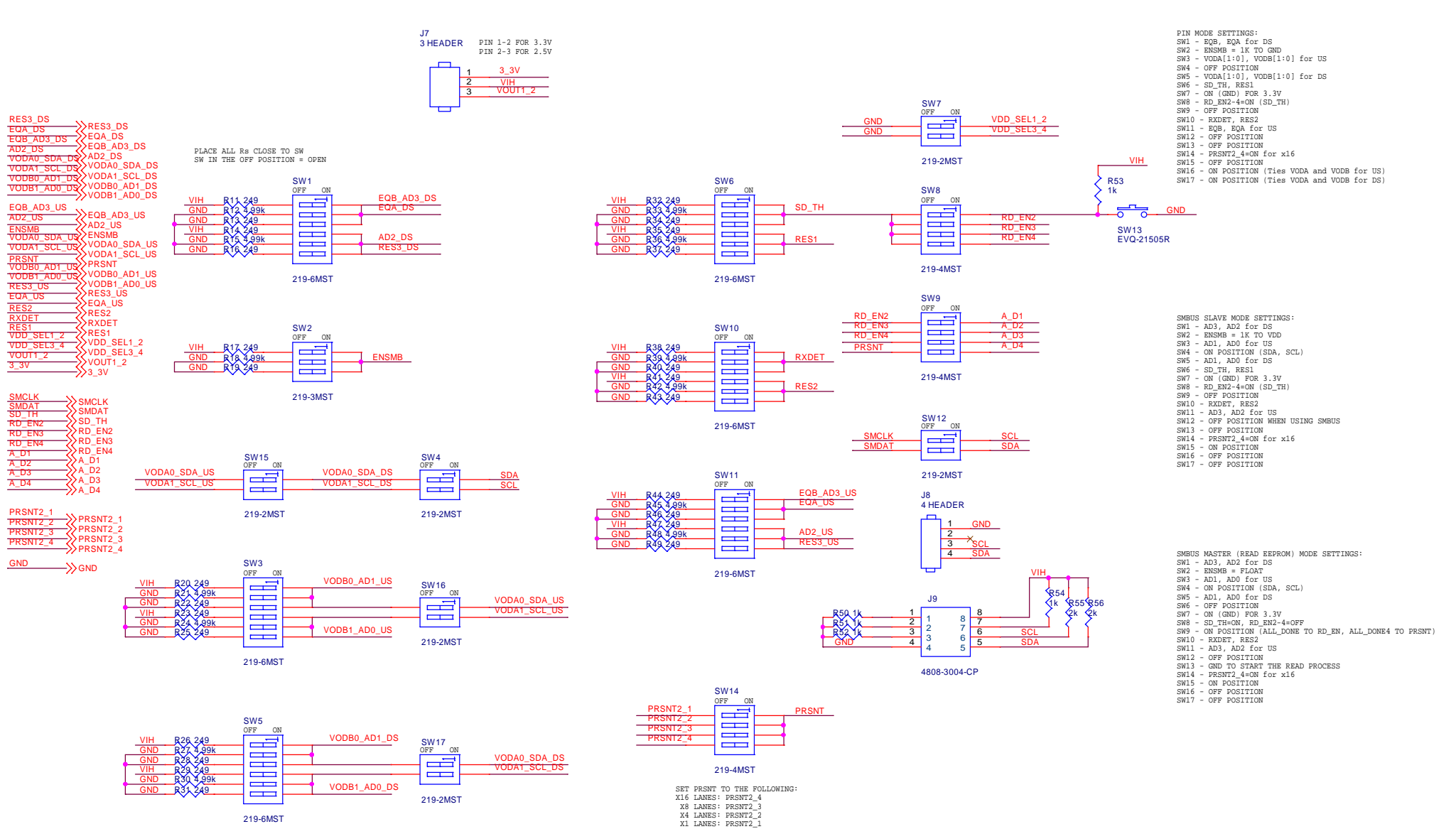


12V	B1	B1	A1	A1	PRSN1
12V	B2	B2	A2	A2	12V
12V	B3	B3	A3	A3	12V
GND	B4	B4	A4	A4	GND
SMCLK	B5	B4	A4	A5	JTAG2
SMDAT	B6	B6	A6	A6	JTAG3
GND	B7	B7	A7	A7	JTAG4
3.3V	B8	B8	A8	A8	JTAG5
JTAG1	B9	B8	A8	A9	3.3V
3.3VAUX	B10	B9	A9	A10	3.3V
WAKE	B11	B10	A10	A11	PERST
RSVD1	B12	B11	A11	A12	GND
GND	B13	B12	A12	A13	REFCLKp
PETp0C31	B14	B13	A13	A14	REFCLKn
PETn0C32	B15	B14	A14	A15	GND
GND	B16	B15	A15	A16	A16_63 0.22uF PERp0
PRSN1_2	B17	B16	A16	A17	A17_64 0.22uF PERn0
GND	B18	B17	A17	A18	GND
PETp1C33	B19	B18	A18	A19	RSVD
PETn1C34	B20	B19	A19	A20	GND
GND	B21	B20	A20	A21	A21_65 0.22uF PERp1
GND	B22	B21	A21	A22	A22_66 0.22uF PERn1
PETp2C35	B23	B22	A22	A23	GND
PETn2C36	B24	B23	A23	A24	GND
GND	B25	B24	A24	A25	A25_67 0.22uF PERp2
GND	B26	B25	A25	A26	A26_68 0.22uF PERn2
PETp3C37	B27	B26	A26	A27	GND
PETn3C38	B28	B27	A27	A28	GND
GND	B29	B28	A28	A29	A29_69 0.22uF PERp3
GND	B30	B29	A29	A30	A30_70 0.22uF PERn3
RSV2	B31	B30	A30	A31	GND
PRSN1_2	B32	B31	A31	A32	RSVD3
GND	B33	B32	A32	A33	RSVD4
PETp4C39	B34	B33	A33	A34	GND
PETn4C40	B35	B34	A34	A35	A35_71 0.22uF PERp4
GND	B36	B35	A35	A36	A36_72 0.22uF PERn4
GND	B37	B36	A36	A37	GND
PETp5C41	B38	B37	A37	A38	GND
PETn5C42	B39	B38	A38	A39	A39_73 0.22uF PERp5
GND	B40	B39	A39	A40	A40_74 0.22uF PERn5
PETp6C43	B41	B40	A40	A41	GND
PETn6C44	B42	B41	A41	A42	GND
GND	B43	B42	A42	A43	A43_75 0.22uF PERp6
GND	B44	B43	A43	A44	A44_76 0.22uF PERn6
PETp7C45	B45	B44	A44	A45	GND
PETn7C46	B46	B45	A45	A46	GND
GND	B47	B46	A46	A47	A47_77 0.22uF PERp7
PRSN1_2	B48	B47	A47	A48	A48_78 0.22uF PERn7
GND	B49	B48	A48	A49	GND
PETp8C47	B50	B49	A49	A50	RSVD5
GND	B51	B50	A50	A51	GND
GND	B52	B51	A51	A52	A52_79 0.22uF PERp8
GND	B53	B52	A52	A53	A53_80 0.22uF PERn8
GND	B54	B53	A53	A54	GND
PETp9C49	B55	B54	A54	A55	GND
PETn9C50	B56	B55	A55	A56	A56_81 0.22uF PERp9
GND	B57	B56	A56	A57	A57_82 0.22uF PERn9
PETp10C51	B58	B57	A57	A58	GND
PETn10C52	B59	B58	A58	A59	GND
GND	B60	B59	A59	A60	A60_83 0.22uF PERp10
GND	B61	B60	A60	A61	A61_84 0.22uF PERn10
PETp11C53	B62	B61	A61	A62	GND
PETn11C54	B63	B62	A62	A63	GND
GND	B64	B63	A63	A64	A64_85 0.22uF PERp11
GND	B65	B64	A64	A65	A65_86 0.22uF PERn11
PETp12C55	B66	B65	A65	A66	GND
PETn12C56	B67	B66	A66	A67	A67_87 0.22uF PERp12
GND	B68	B67	A67	A68	A68_88 0.22uF PERn12
GND	B69	B68	A68	A69	GND
PETp13C57	B70	B69	A69	A70	GND
PETn13C58	B71	B70	A70	A71	A71_89 0.22uF PERp13
GND	B72	B71	A71	A72	A72_90 0.22uF PERn13
GND	B73	B72	A72	A73	GND
PETp14C59	B74	B73	A73	A74	GND
PETn14C60	B75	B74	A74	A75	A75_91 0.22uF PERp14
GND	B76	B75	A75	A76	A76_92 0.22uF PERn14
GND	B77	B76	A76	A77	GND
PETp15C61	B78	B77	A77	A78	GND
PETn15C62	B79	B78	A78	A79	GND
GND	B80	B79	A79	A80	A80_93 0.22uF PERp15
PRSN1_2	B81	B80	A80	A81	A81_94 0.22uF PERn15
RSVD2	B82	B81	A81	A82	GND
GND	B82	B82	A82	A82	GND

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